

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL TO BE IT 180A (ROHS COMPLIANT MATERIAL) OR EQUIVALENT GLASS  
TRANSITION TEMPERATURE MUST MEET OR EXCEED THE TEMPERATURE EXHIBITED  
WITH HIGH TEMPERATURE PROCESSES ASSOCIATED WITH LEAD FREE ASSEMBLY.
- LAMINATE AND PRE-PREG MATERIAL SHALL BE IN ACCORDANCE WITH IPC4101/24,  
MINIMUM Tg = 170 C.
- SOLDERMASK TO BE IN ACCORDANCE WITH IPC-SM-850, CLASS T, LIQUID  
PHOTIMAGABLE, COLOR GREEN, USE APPROPRIATE SOLDER MASK ARTWORK FOR EACH
- APPLY SILKSCREEN (LEGEND) OVER SOLDERMASK USING A NON-CONDUCTIVE EPOXY  
INK, COLOR WHITE, VENDOR HAVE TO CLIP SILKSCREEN FROM ANY EXPOSED COPPER FEATURE.
- CONDUCTIVE FEATURES TO BE FINISHED WITH ENIG  
GOLD PER IPC-4552, PLATING TO BE APPLIED BEFORE SOLDERMASK.
- LAYER TO LAYER REGISTRATION TO BE WITHIN +/-0.003".
- WARP AND TWIST SHALL NOT EXCEED 0.010"/1".
- ALL FAB NOTESS ARE IN INCHES.
- DESIGN RULES:
  - MINIMUM COPPER WIDTH IS .003".
  - MINIMUM COPPER-TO-COPPER IS .003".
- FABRICATE BOARDS IN ACCORDANCE WITH IPC-6012, CLASS 2, FINISHED BOARDS  
MUST MEET QUALITY CONFORMANCE TESTING AND INSPECTION AS SPECIFIED THEREIN.  
BOARD FABRICATOR SHALL APPLY DATE CODE AND UL-796 APPROVAL  
MARKING TO PRIMARY SIDE WHERE INDICATED, MARKING TO BE IN COPPER, ETCHED.
- NO CHANGES TO GERBER DATA PACKAGE ALLOWED WITHOUT PRIOR APPROVAL.
- GERBER FILES MUST BE 100% NETLIST TESTED TO INCLUDED IPC-356 FILE.
- DRILLED SLOTS INDICATED BY MULTIPLE DRILL HITS TO BE FINISHED AS SMOOTH SLOTS.
- DIELECTRICS AND LINEWIDTHS MAY BE ADJUSTED TO MEET THE IMPEDANCE  
REQUIREMENTS WITH APPROVALS.
- FOR PANELIZATION PLEASE CONTACT eINFOCHIPS.
- ADD 5MM ROVERSTRIP ON TWO SIDES OF PCB.
- ALL VIAS ARE MASKED.

DIFFERENTIAL PAIR\_100-OHM

LAYER NO.	CONDUCTOR WIDTH	SPACING	REFERENCE LAYER	IMPEDANCE +/-10%
LAYER 1	3.7 MIL	6.3 MIL	2	100-OHMS +/-10%
LAYER 3	4 MIL	8 MIL	2/4	100-OHMS +/-10%
LAYER 5	4 MIL	8 MIL	4/6	100-OHMS +/-10%
LAYER 10	4 MIL	8 MIL	9/11	100-OHMS +/-10%
LAYER 12	3.7 MIL	6.3 MIL	11	100-OHMS +/-10%

DIFFERENTIAL PAIR\_90-OHM

LAYER NO.	CONDUCTOR WIDTH	SPACING	REFERENCE LAYER	IMPEDANCE +/-10%
LAYER 1	4.252 MIL	4.948 MIL	2	100-OHMS +/-10%
LAYER 3	4 MIL	4.5 MIL	2/4	100-OHMS +/-10%
LAYER 5	4 MIL	4.5 MIL	4/6	100-OHMS +/-10%
LAYER 10	4 MIL	4.5 MIL	9/11	100-OHMS +/-10%
LAYER 12	4.252 MIL	4.948 MIL	11	100-OHMS +/-10%

SINGLE ENDED

LAYER NO.	CONDUCTOR WIDTH	REFERENCE LAYER	IMPEDANCE +/-10%
LAYER 1	5.656 MIL	2	50-OHMS +/-10%
LAYER 3	4 MIL	2/4	50-OHMS +/-10%
LAYER 5	4 MIL	4/6	50-OHMS +/-10%
LAYER 10	4 MIL	9/11	50-OHMS +/-10%
LAYER 12	5.656 MIL	11	50-OHMS +/-10%

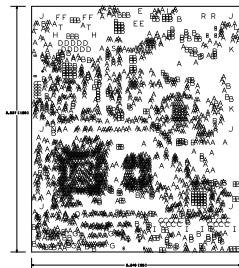
SINGLE ENDED

LAYER NO.	CONDUCTOR WIDTH	REFERENCE LAYER	IMPEDANCE +/-10%
LAYER 1	9 MIL	2	42-OHMS +/-10%
LAYER 3	6 MIL	2/4	42-OHMS +/-10%
LAYER 10	6 MIL	9/11	42-OHMS +/-10%
LAYER 12	9 MIL	11	42-OHMS +/-10%

REV		DATE
1.0	FIRST RELEASE	04/10/2018
2.0	BETA RELEASE	28/01/2019
3.0	BETA2 RELEASE	30/04/2019

LAYER STACK-UP

-----	PRIMARY SIDE, SILK SCREEN	
=====	PRIMARY SIDE, SOLDER MASK 1 MIL	
=====	PRIMARY SIDE, LAYER 1	2.55 MIL
=====	DIELECTRIC	4.164 MIL
=====	L02_GND_1	0.709 MIL
=====	DIELECTRIC	4.488 MIL
=====	L03_SIG_1	0.709 MIL
=====	DIELECTRIC	5.733 MIL
=====	L04_GND_2	0.709 MIL
=====	DIELECTRIC	4.488 MIL
=====	L05_SIG_2	0.709 MIL
=====	DIELECTRIC	5.733 MIL
=====	L06_POWER_1	0.709 MIL
=====	DIELECTRIC	4.488 MIL
=====	L07_POWER_2	0.709 MIL
=====	DIELECTRIC	5.733 MIL
=====	L08_SIG_3	0.709 MIL
=====	DIELECTRIC	4.488 MIL
=====	L09_GND_3	0.709 MIL
=====	DIELECTRIC	5.733 MIL
=====	L10_SIG_4	0.709 MIL
=====	DIELECTRIC	4.488 MIL
=====	L11_GND_4	0.709 MIL
=====	DIELECTRIC	4.164 MIL
=====	SECONDARY SIDE, LAYER 12	2.55 MIL
=====	SECONDARY SIDE, SOLDER MASK 1 MIL	
-----	SECONDARY SIDE, SILK SCREEN	



eInfochips	
DATE: 30/04/2019	
DESIGNED AT: eInfochips	
PART NO/CARD REF: ARROW IMX8XML RD BOARD	REV: 3.0
FILM LAYER: FABRICATION LAYER	

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS					
FIGURE	FINISHED SIZE	ROTATION	TOLERANCE_DRILL	PLATED	QTY
A	8.0	-	+1.0/-1.0	PLATED	1784
B	12.0	-	+3.0/-3.0	PLATED	275
C	28.0	-	+3.0/-3.0	PLATED	28
D	35.0	-	+3.0/-3.0	PLATED	10
E	40.0	-	+3.0/-3.0	PLATED	3
F	47.0	-	+3.0/-3.0	PLATED	4
G	51.18	-	+3.0/-3.0	PLATED	4
H	63.0	-	+3.0/-3.0	PLATED	2
I	91.0	-	+2.0/-2.0	PLATED	4
J	100.0	-	+3.0/-0.0	PLATED	6
K	126.0	-	+3.0/-3.0	PLATED	2
L	32.0	-	+3.0/-3.0	NON-PLATED	4
M	32.0	-	+3.0/-3.0	NON-PLATED	1
N	34.0	-	+3.0/-3.0	NON-PLATED	2
P	44.0	-	+3.0/-3.0	NON-PLATED	1
Q	48.0	-	+3.0/-3.0	NON-PLATED	1
R	51.0	-	+3.0/-3.0	NON-PLATED	2
S	63.0	-	+3.0/-3.0	NON-PLATED	1
T	128.0	-	+3.0/-3.0	NON-PLATED	2
+	33.46x27.56	0.000	+3.0/-3.0	PLATED	2
+	33.46x27.56	90.000	+3.0/-3.0	PLATED	2
+	51.18x23.62	0.000	+3.0/-3.0	PLATED	2
+	51.18x23.62	90.000	+3.0/-3.0	PLATED	2
+	63.0x32.0	90.000	+3.0/-3.0	PLATED	3

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN		eInfochips	
<input checked="" type="checkbox"/> INCHES	<input type="checkbox"/> MILLIMETERS	DRAWING TITLE ARROW_IMX8XML_RD BOARD	
DATE 30/04/2019	SIZE D	PART NUMBER 17_00644_03	REV 3.0
SCALE 1/1		SHEET 1 OF 1	